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In the Claims:

This listing of claims will replace all prior versions and listings, of claims in the application:

1. (currently amended) A pressure sensor module comprising:
a base structure; and
~~a cantilever member formed in the base structure by an isolation gap; and~~
~~a pressure sensor adhered to the base structure via an adhesive layer, said pressure~~
~~sensor comprising a pressure sensing element, wherein the adhesive layer adheres only a first~~
~~portion of the pressure sensor to the base structure to create an isolation gap between a second~~
~~portion of the sensor and the base structure, wherein the isolation gap forms a ~~located on the~~~~
~~cantilever member, wherein the cantilever member ~~via the second portion of the sensor that~~~~
provides stress isolation to the pressure sensing element.
2. (cancelled)
3. (cancelled)
4. (currently amended) The pressure sensor module as defined in claim [[2]] 1, wherein
~~the first member~~ sensor comprises a sensor cell further comprising electrical circuitry.
5. (currently amended) The pressure sensor module as defined in claim [[2]] 1, wherein
~~the second member~~ base structure comprises a substrate.
6. (cancelled)
7. (cancelled)
8. (cancelled)

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9. (currently amended) A pressure sensor module comprising:

a base structure comprising a first member and a second member fixed to the first member;

an adhesive layer adhering only a first portion of the first member to the second member to create an isolation gap between a second portion of the first member and the second members, wherein a cantilever member is formed in via the base structure second portion of the first member by an the isolation gap; and

a pressure sensing element located on the cantilever member, wherein the cantilever member provides stress isolation to the pressure sensing element.

10. (cancelled)

11. (original) The pressure sensor module as defined in claim 9, wherein the first member comprises a sensor cell comprising electrical circuitry and connected to the second member, wherein the pressure sensing element is located on the sensor cell.

12. (original) The pressure sensor module as defined in claim 9, wherein the base structure further comprises a housing connected to the second member.

13. (cancelled)

14. (cancelled)

15. (currently amended) A method of forming a stress isolated pressure sensor module comprising the steps of:

providing a base structure;

forming an isolation gap in the base structure to form a cantilever member applying an adhesive layer to a portion of the base structure; and

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disposing adhering a pressure sensor comprising a pressure sensing element on onto the base structure via the adhesive layer, wherein the pressure sensor is adhered onto a portion of the base structure to create an isolation gap between a remaining portion of the pressure sensor, wherein the cantilever member above is formed by the isolation gap so that the cantilever member provides stress isolation to the pressure sensing element.

16. (original) The method as defined in claim 15, wherein the step of providing a base structure comprises forming a first member on top of a second member, wherein the pressure sensing element is disposed on the first member.

17. (original) The method as defined in claim 16, wherein the first member is adhered to only a portion of the second member such that the isolation gap is formed between the first and second members and the first member forms the cantilever member.

18. (cancelled)

19. (cancelled)

20. (cancelled)